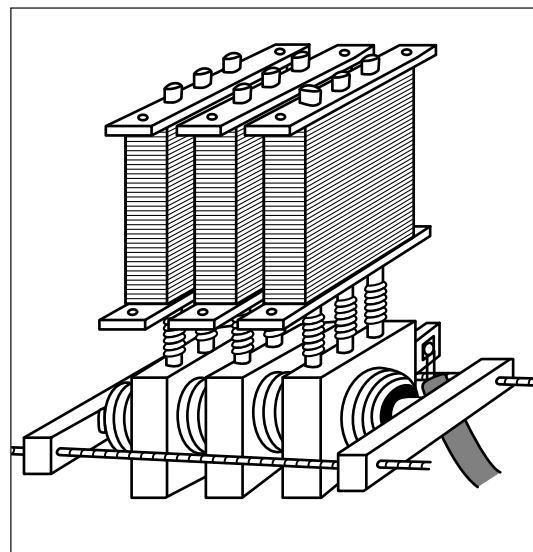




TRANSCAL® PRESS PACK SEMICONDUCTORS HEATPIPE SYSTEMS

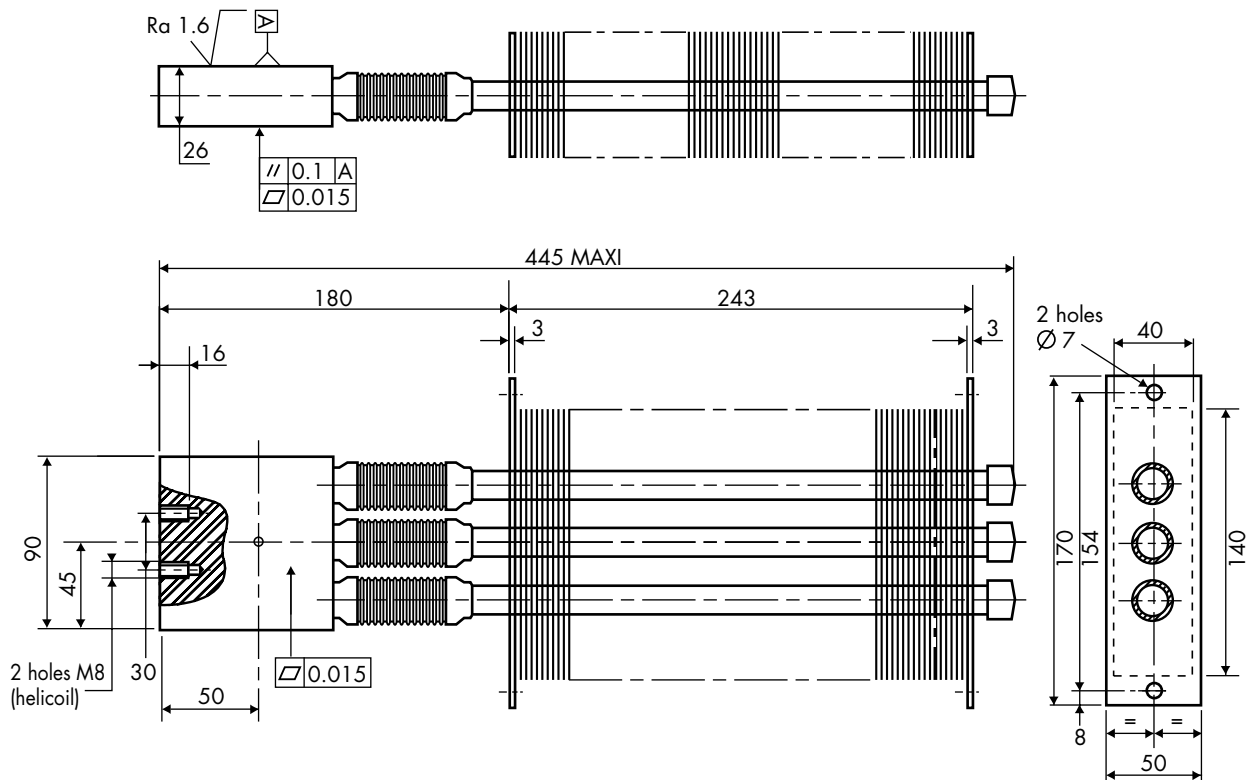


- USED IN TRACTION CONVERTERS,
TRANSIT CARS, TRAMWAYS, LOCOMOTIVES...
- LIGHTER THAN EXTRUDED PROFILE.
- MAINTENANCE FREE,
IF COMPARED WITH WATER SYSTEMS.
- HIGH RELIABILITY : FERRAZ KNOW HOW.
- WIDE RANGE AVAILABLE.

SC 86 TYPE

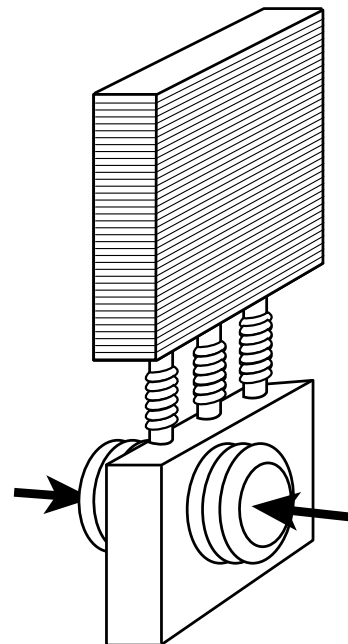
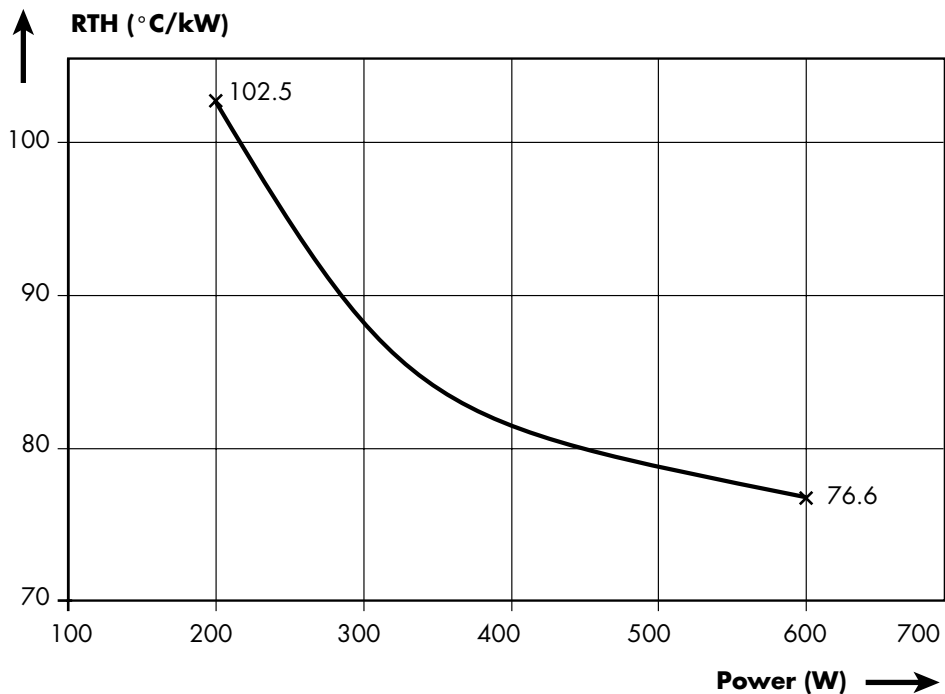
POWER DISSIPATION.....	Up to 600 W (300 W per side) with 48 mm semiconductor dissipating diameter
THERMAL RESISTANCE RANGE.....	From 0.102°C/W to 0.077°C/W at 20°C ambient
SURFACE TEMPERATURE RISE.....	Max 46°C at 4 m/s airspeed (788 fpm)
PRESSURE DROP	< 12.7 mm of water at 4 m/s airspeed (< 124.6 Pa)
SEMICONDUCTOR TO FIN ELECTRICAL INSULATION	9.5 kV 50 Hz 1'
WORKING FLUID.....	Freon substitute FC72
MECHANICAL SHOCKS AND VIBRATIONS BEHAVIOUR	According to IEC 77 Traction Standard
PRESSPACK SEMICONDUCTORS	Up to 80 mm diameters
CLAMPING FORCE	Max 40 kN
WEIGHT	2.5 Kg

OUTLINE DRAWINGS (mm)



EXAMPLE OF THERMAL FEATURES

Thermal resistance vs dissipated power at 20°C ambient.



Dissipated power (W) by two 48 mm diameter diodes.

Clamping force < 22 kN.

Air speed 4 m/s (788 fpm).

FERRAZ

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